

Aptek 2205 A/B Low modulus urethane stacking compound

Category : Polymer , Adhesive , Thermoset , Polyurethane, TS , Thermoset Polyurethane, Adhesive

Material Notes:

APTEK 2205-A/B is a thixotropic, two component, electrically insulating, low modulus urethane system designed for the staking of electrical/electronic components to printed circuit boards. Although APTEK 2205-A/B is capable of achieving full cure at room temperature, a short term exposure to moderate heat will greatly reduce processing time and optimize cured properties. Good wet strength holds components in place allowing for the movement of the circuit boards during processing; 100% solids, solvent free system that will not form voids during cure or service life; Low Tg for excellent low-temperature cycling and performance; Very good substrate adhesion, superior to silicones; Available at two levels of reactivity to meet various productivity needs; available in pre-weighted kits to minimize handling time; ideal for field repair operations. APTEK 2205-A is a filled polyol resin that is safe to handle when used properly.. APTEK 2205-B is an organic isocyanate which make cause severe eye and skin irritation with direct contact.. Information provided by Aptek Laboratories, Inc.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Aptek-2205-AB-Low-modulus-urethane-stacking-compound.php

Physical Properties	Metric	English	Comments
Density	0.990 g/cc	0.0358 lb/in ³	A Component; ASTM D1475
	1.21 g/cc	0.0437 lb/in ³	B Component; ASTM D1475
Viscosity	88 cP	88 cP	B Component; ASTM D1824

Mechanical Properties	Metric	English	Comments
Hardness, Shore A	65	65	Cured property; ASTM D2240
Tensile Strength, Ultimate	6.03 MPa	875 psi	Cured property; ASTM D412
Elongation at Break	265 %	265 %	Cured property; ASTM D412

Thermal Properties	Metric	English	Comments
CTE, linear	79.0 $\mu\text{m/m-}^{\circ}\text{C}$	43.9 $\mu\text{in/in-}^{\circ}\text{F}$	Cured property; alpha 1; JMTP P200
	@Temperature 20.0 $^{\circ}\text{C}$	@Temperature 68.0 $^{\circ}\text{F}$	
	185 $\mu\text{m/m-}^{\circ}\text{C}$	103 $\mu\text{in/in-}^{\circ}\text{F}$	Cured property; alpha 2; JMTP P200
	@Temperature 20.0 $^{\circ}\text{C}$	@Temperature 68.0 $^{\circ}\text{F}$	
Glass Transition Temp, Tg	-70.0 $^{\circ}\text{C}$	-94.0 $^{\circ}\text{F}$	Cured property; JMTP P-200
Flash Point	$\geq 125^{\circ}\text{C}$	$\geq 257^{\circ}\text{F}$	B Component; ASTM D92
	$\geq 150^{\circ}\text{C}$	$\geq 302^{\circ}\text{F}$	A Component; ASTM D92

Electrical Properties	Metric	English	Comments
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Electrical Properties	Metric	English	Comments
	1.30×10^{15} ohm-cm	1.30×10^{15} ohm-cm	Cured property; ASTM D257
Dielectric Constant	3.5	3.5	Cured property; ASTM D150
	@Frequency 1000 Hz	@Frequency 1000 Hz	
Dissipation Factor	0.030	0.030	Cured property; ASTM D150
	@Frequency 1000 Hz	@Frequency 1000 Hz	

Processing Properties	Metric	English	Comments
Processing Temperature	85.0 °C	185 °F	Cure 4 hrs

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